

1. General description

Dual Silicon Carbide Schottky diode in a TO247 plastic package, designed for high frequency switched-mode power supplies.



2. Features and benefits

- Highly stable switching performance
- High forward surge capability I_{FSM}
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant
- High junction operating temperature capability ($T_{j(max)} = 175\text{ °C}$)

3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

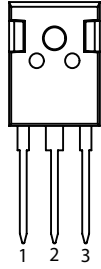
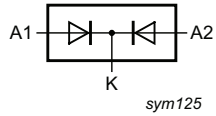
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V_{RRM}	repetitive peak reverse voltage			1200			V
$I_{O(AV)}$	limiting average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 148\text{ °C}$; both diodes conducting; Fig. 1 ; Fig. 2 ; Fig. 3		10			A
T_j	junction temperature			-55 to 175			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	$I_F = 5\text{ A}$; $T_j = 25\text{ °C}$; per diode; Fig. 5		-	1.42	1.60	V
		$I_F = 5\text{ A}$; $T_j = 150\text{ °C}$; per diode; Fig. 5		-	1.90	2.30	V
		$I_F = 5\text{ A}$; $T_j = 175\text{ °C}$; per diode; Fig. 5		-	2.00	2.50	V
Dynamic characteristics							
Q_r	recovered charge	$I_F = 5\text{ A}$; $dI_F/dt = 500\text{ A}/\mu\text{s}$; $V_R = 400\text{ V}$; $T_j = 25\text{ °C}$; per diode; Fig. 7		-	11	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode		
2	K	cathode		
3	A2	anode		
mb	mb	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2D101200CW	TO247	WNSC2D101200CW6Q	Tube	30	SOT429 (L)	25-Mar-2013
					TO247P (P)	31-Mar-2023

7. Marking

Table 4. Marking codes

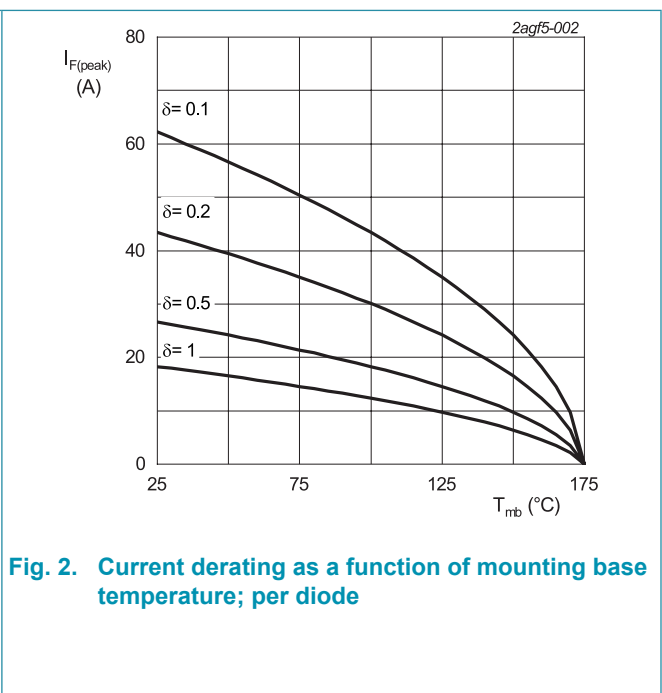
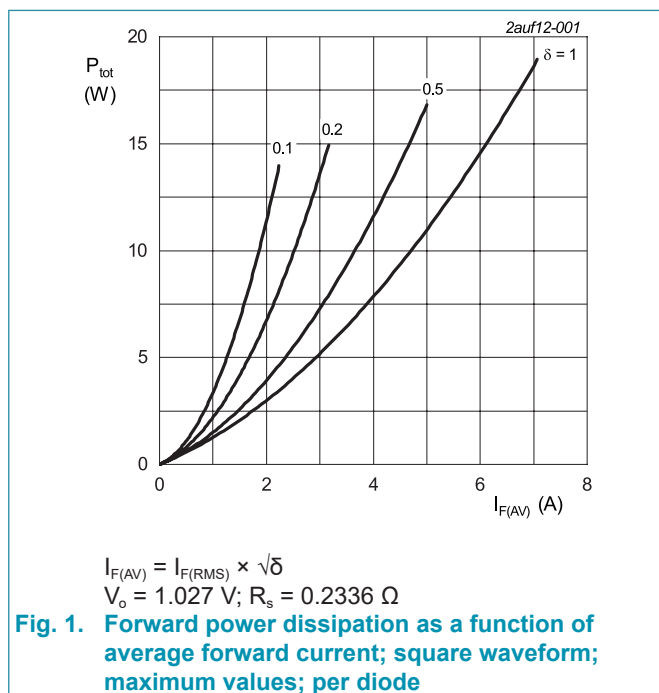
Type number	Marking codes
WNSC2D101200CW	WNSC2D 101200CW

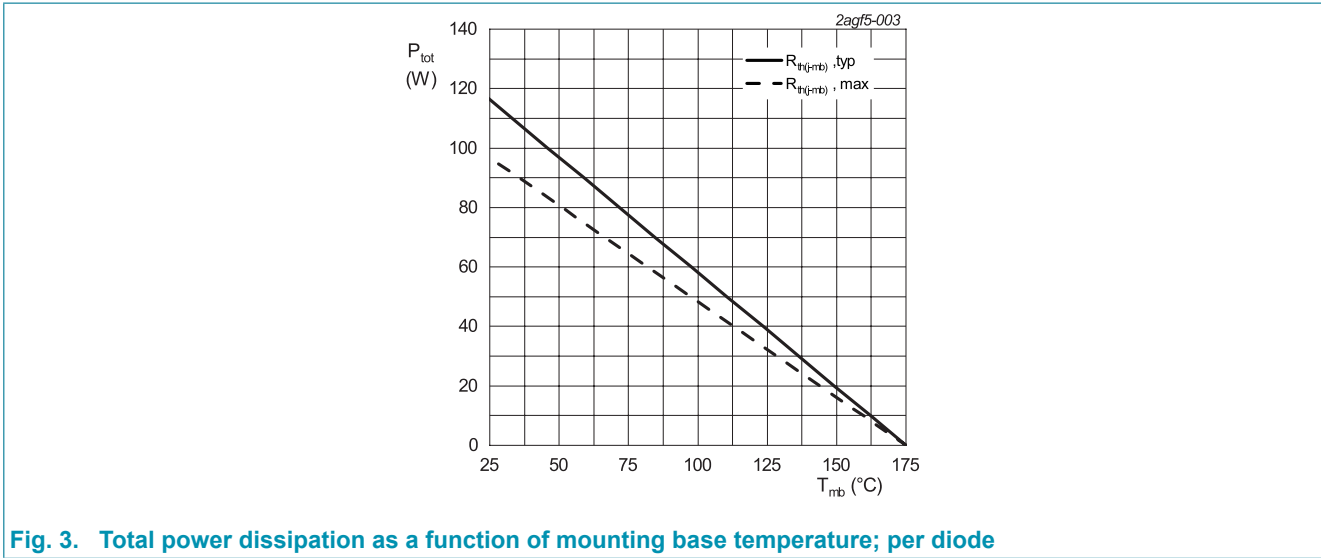
8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			1200	V
V_{RWM}	crest working reverse voltage			1200	V
V_R	reverse voltage	DC		1200	V
$I_{O(AV)}$	limiting average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 148\text{ °C}$; both diodes conducting; Fig. 1 ; Fig. 2 ; Fig. 3		10	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\ \mu\text{s}$; $T_{mb} \leq 149\text{ °C}$; square-wave pulse; per diode		10	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ °C}$; sine-wave pulse; per diode		45	A
		$t_p = 10\ \mu\text{s}$; $T_{j(\text{init})} = 25\text{ °C}$; square-wave pulse; per diode		450	A
I^2t	I^2t for fusing	sine-wave pulse; $T_{j(\text{init})} = 25\text{ °C}$; $t_p = 10\text{ ms}$		10.13	A^2s
T_{stg}	storage temperature			-55 to 175	$^{\circ}\text{C}$
T_j	junction temperature			-55 to 175	$^{\circ}\text{C}$





9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	per diode; Fig. 4		-	1.29	1.55	K/W
		both diodes conducting		-	0.65	0.8	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

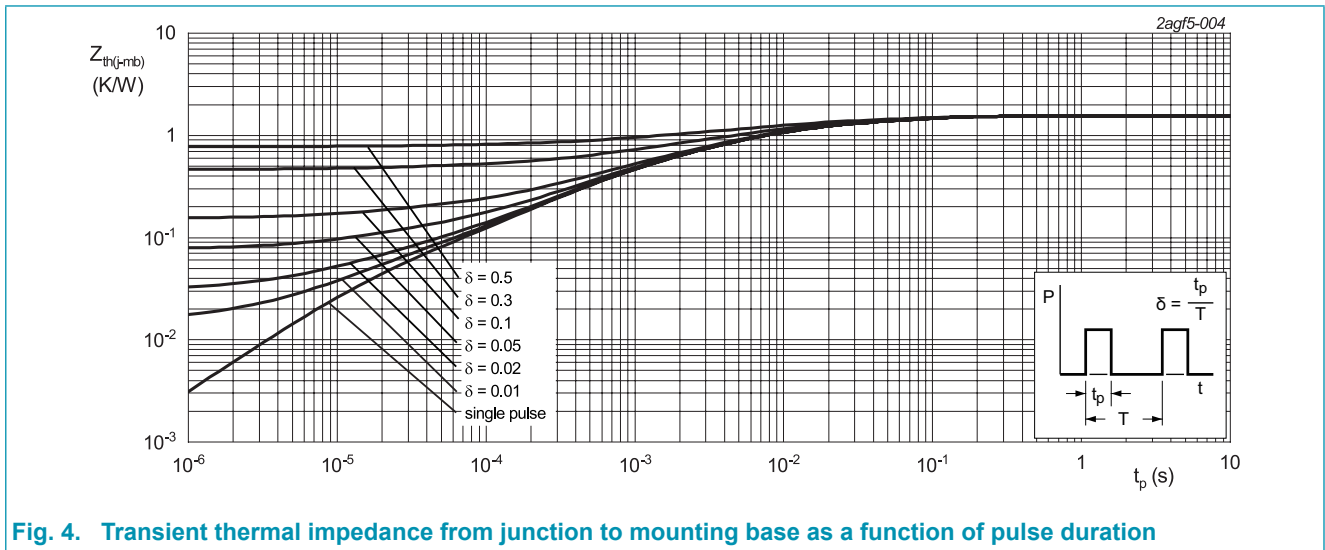
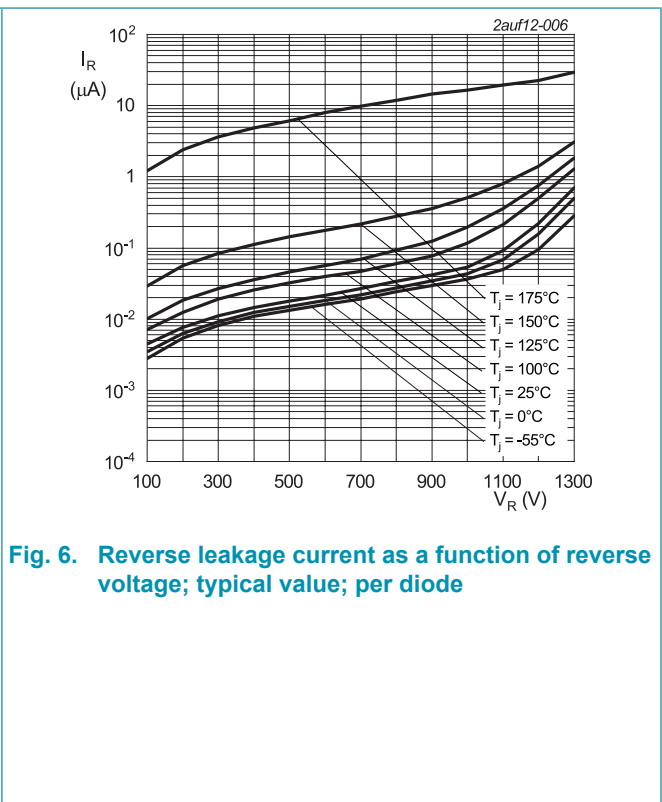
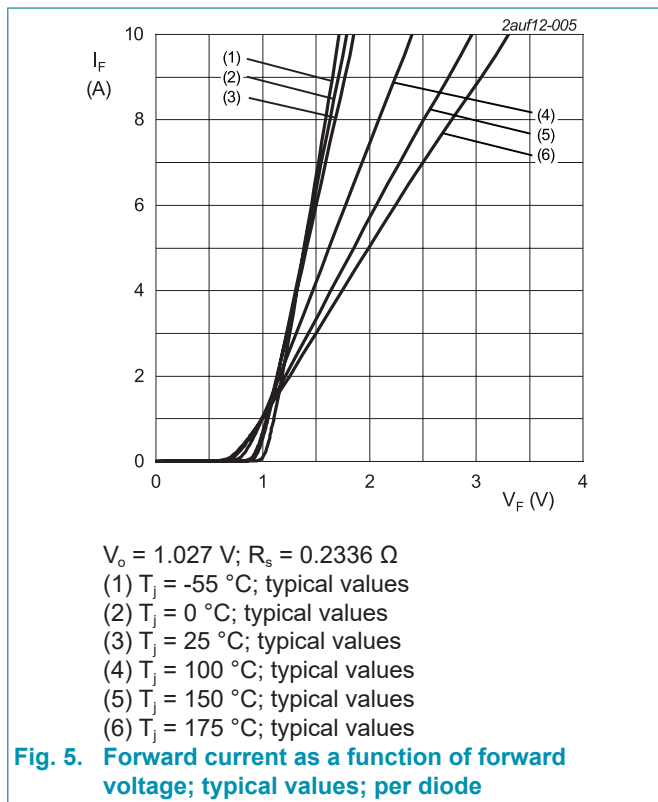


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
I_F	forward current	$I_F = 5 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$ per diode; Fig. 5		-	1.42	1.60	V
		$I_F = 5 \text{ A}; T_j = 150 \text{ }^\circ\text{C};$ per diode; Fig. 5		-	1.90	2.30	V
		$I_F = 5 \text{ A}; T_j = 175 \text{ }^\circ\text{C};$ per diode; Fig. 5		-	2.00	2.50	V
I_R	reverse current	$V_R = 1200 \text{ V}; T_j = 25 \text{ }^\circ\text{C};$ per diode; Fig. 6		-	0.5	25	μA
		$V_R = 1200 \text{ V}; T_j = 175 \text{ }^\circ\text{C};$ per diode; Fig. 6		-	25	300	μA
Dynamic characteristics							
Q_r	recovered charge	$I_F = 5 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C};$ per diode; Fig. 7		-	11	-	nC
C_d	diode capacitance	$f = 1 \text{ MHz}; V_R = 1 \text{ V}; T_j = 25 \text{ }^\circ\text{C};$ per diode		-	260	-	pF
		$f = 1 \text{ MHz}; V_R = 400 \text{ V}; T_j = 25 \text{ }^\circ\text{C};$ per diode		-	22	-	pF
		$f = 1 \text{ MHz}; V_R = 800 \text{ V}; T_j = 25 \text{ }^\circ\text{C};$ per diode		-	16	-	pF
E_{as}	non-repetitive avalanche energy	$I_R = 2.9 \text{ A}; L = 10 \text{ mH}; T_{j(\text{init})} = 25 \text{ }^\circ\text{C};$ per diode		42	-	-	mJ



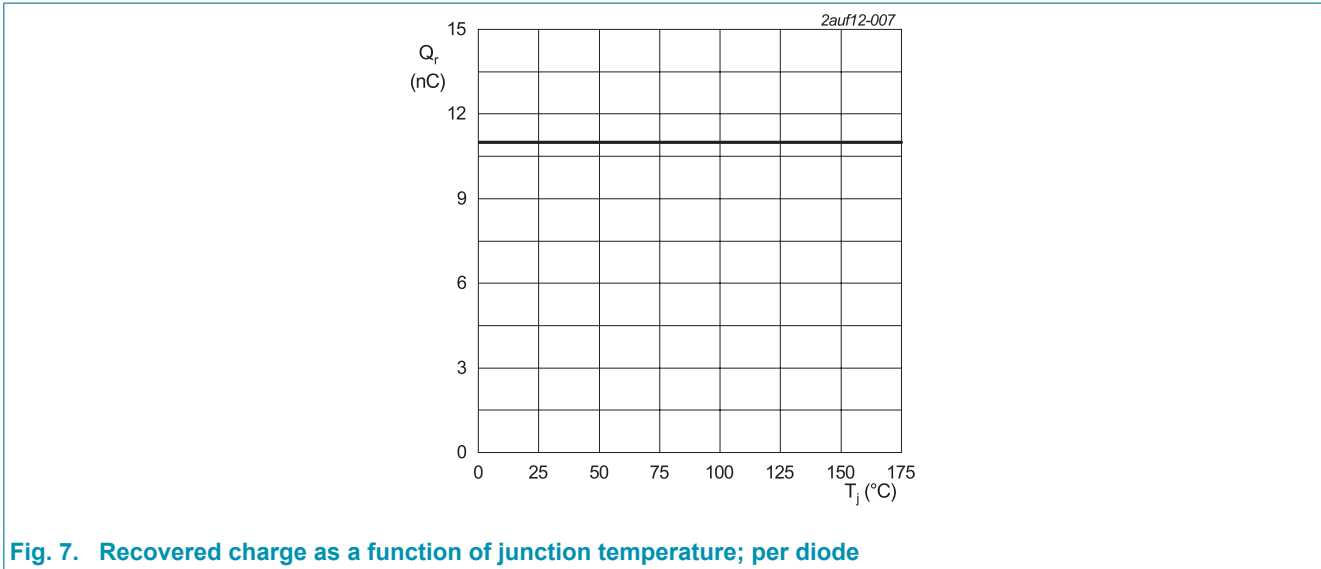
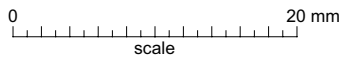
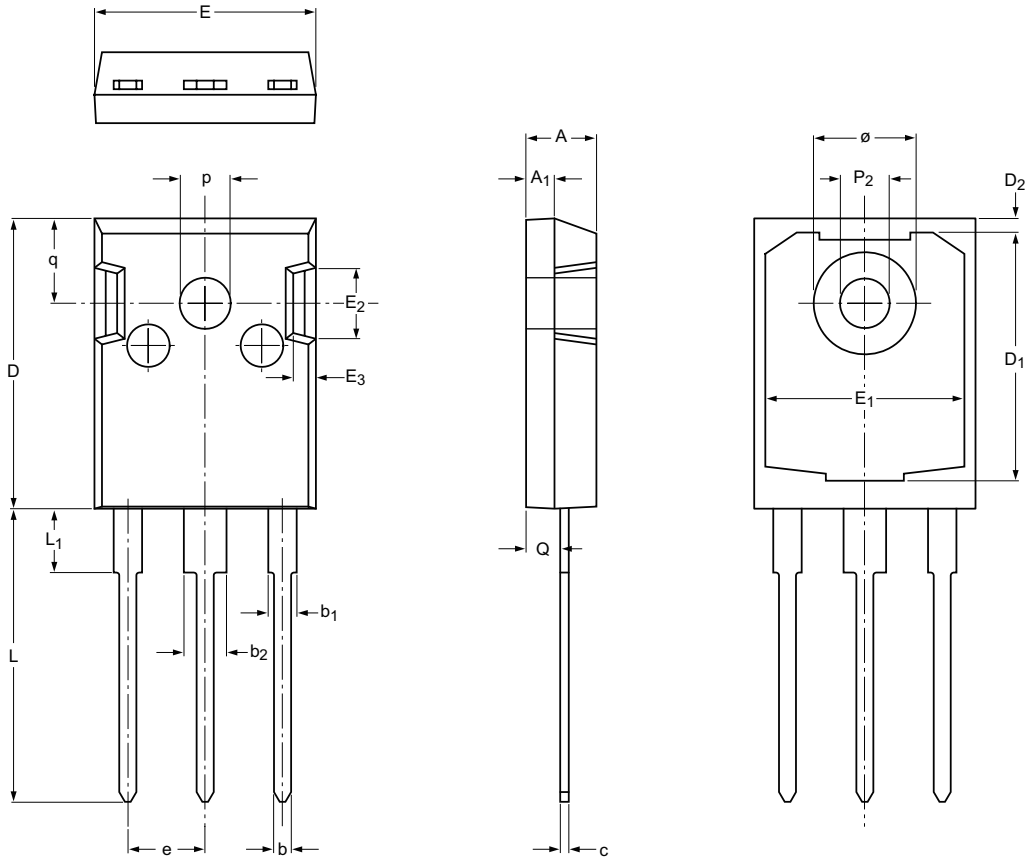


Fig. 7. Recovered charge as a function of junction temperature; per diode

11. Package outline

Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 3-lead TO-247

SOT429



Dimensions (mm are the original dimensions)

Unit ⁽¹⁾	A	A ₁	b	b ₁	b ₂	c	D	D ₁	D ₂	E	E ₁	E ₂	E ₃	e ⁽¹⁾	L	L ₁	P ₂	p	Q	q	ø		
max	5.20	2.10	1.40	2.20	3.20	0.70	20.6	17.68	1.20	15.75	14.22	5.20	1.80	5,45	20.90	4.75	3.60	3.70	2.60	6.18	7.30		
nom																							
min	4.70	1.90	1.00	1.80	2.80	0.50	20.3	17.28	0.80	15.45	13.82	4.80	1.40			20.40	4.25	3.40	3.50	2.20	5.78	7.10	

Note

1. Basic spacing between centers.

sot429_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT429	TO-247				04-09-14- 13-03-25

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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